

## **For Immediate Release**

### **Palomar Technologies Wins 2007 Advanced Packaging Award for Wire Bonder Capabilities**

**Carlsbad, Calif. – August 1, 2007** – Palomar Technologies, provider of precision automation equipment, process development, and assembly services for microelectronic assembly, announces it has received the 2007 Advanced Packaging Award in the wire bonding equipment category for the use of its Model 8000 ball bonder to emulate certain wedge bonding applications. Sponsored by *Advanced Packaging* magazine, the awards salute novel solutions, innovation, and technological advancements. Awards were presented during a ceremony on July 18, 2007, held in conjunction with SEMICON West, the semiconductor industry's preeminent trade show.

Palomar uses its Model 8000 ball bonder for certain low-profile interconnects, fine pitch, running-stitch interconnects, and die-to-die bonding where a wedge bonder may have traditionally been used. Using a specially developed chain bonding stitch-stitch interconnect, this technique offers higher bonding rates than traditional wedge bonding. An evaluation of how this process may improve or replace your wedge bonding requirements is available by contacting Palomar Technologies at [info@bonders.com](mailto:info@bonders.com).

Award recipients are selected by a panel of industry experts (not employed by PennWell or *Advanced Packaging*) that evaluates each submission based on: its ability to meet a significant industry challenge; creative application of a new or existing technology; overall quality and consistency of performance; economic merits; and throughput characteristics. Products are judged specifically on their innovation, cost-effectiveness, speed/throughput improvements, quality, ease-of-use, maintainability/reparability, and environmental responsibility.

*Advanced Packaging* magazine, with a circulation of over 22,000, serves businesses that integrate electronic component packages into circuitry of their end products. It is published by PennWell Corporation.

## **About Palomar Technologies**

Palomar Technologies (formerly part of Hughes Aircraft Company) is one of the world's principal suppliers of automated high-precision wire bonders and component placement systems and process development and assembly services to increase yield and lower costs for manufacturers of optoelectronic, RF, and microelectronic packages in the photonics, wireless, microwave, automotive, aerospace, medical, LED, solar, and life sciences industries.

For more information on **Palomar Technologies and Palomar Microelectronics**, visit <http://www.palomartechnologies.com> or contact 760-931-3600.

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